

IN THE CLAIMS:

Please amend the claims, as follows:

Claims 1-21 (canceled).

22. (new) An epoxy hardener composition having a cure temperature of between about 60-100°C, comprising a mixture of imidazole, trimethylolpropane and a tetramethylguanidine adduct formed as a reaction product of tetramethylguanidine and one of a monoepoxide, a diepoxide, a phenol, and a dihydric phenol and formaldehyde.

23. (new) An epoxy hardener composition according to claim 22, wherein the tetramethylguanidine adduct is a reaction product of tetramethylguanidine and a diglycidylether.

24. (new) An epoxy hardener composition having a cure temperature of between about 60-100°C, comprising a mixture of trimethylolpropane, a trihydric compound having methylol groups at the 2- and 6- positions formed by reacting a 4-alkyl phenol with 2 moles of formaldehyde, and a tetramethylguanidine adduct formed as a reaction product of tetramethylguanidine and one of a monoepoxide, a diepoxide, a phenol, and a dihydric phenol and formaldehyde.

25. (new) An epoxy hardener composition according to claim 24, wherein the tetramethylguanidine adduct is a reaction product of tetramethylguanidine and a diglycidylether.

26. (new) An epoxy hardener composition according to claim 24, wherein the trihydric compound is 2, 6-bis(hydroxymethyl)-p-cresol.

27. (new) An epoxy hardener composition having a cure temperature of between about 60-100°C, comprising a mixture of trimethylolpropane, a trihydric compound having methylol groups at the 2- and 6- positions formed by reacting a 4-alkyl phenol with 2 moles of formaldehyde, and tetramethylguanidine.

28. (new) An epoxy hardener composition according to claim 27, wherein the trihydric compound is 2, 6-bis(hydroxymethyl)-p-cresol.